

8A, 650V N-CHANNEL MOSFET

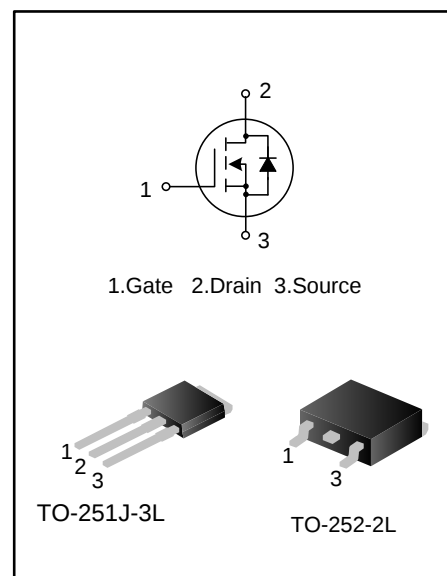
GENERAL DESCRIPTION

SVF8N65RD(MJ) is an N-channel enhancement mode power MOS field effect transistor which is produced using Silan proprietary F-Cell™ high-voltage planar VDMOS technology. The improved process and cell structure have been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are widely used in AC-DC power supplies, DC-DC converters and H-bridge PWM motor drivers.

FEATURES

- ♦ 8A,650V, $R_{DS(on)}(typ)=1.2\Omega@V_{GS}=10V$
- ♦ Low gate charge
- ♦ Low Crss
- ♦ Fast switching
- ♦ Improved dv/dt capability



ORDERING INFORMATION

Part No.	Package	Marking	Hazardous Substance Control	Packing Type
SVF8N65RMJ	TO-251J-3L	8N65RMJ	Halogen free	Tape&Reel
SVF8N65RDTR	TO-252-2L	8N65RD	Halogen free	Tube

ABSOLUTE MAXIMUM RATINGS (T_c=25°C UNLESS OTHERWISE NOTED)

Characteristics		Symbol	Rating	Unit
Drain-Source Voltage		V _{DS}	650	V
Gate-Source Voltage		V _{GS}	±30	V
Drain Current	TC=25°C	I _D	8.0	A
	TC=100°C		5.1	
Drain Current Pulsed		I _{DM}	32	A
Power Dissipation(TC=25°C) -Derate above 25°C		P _D	104	W
			0.8	W/°C
Single Pulsed Avalanche Energy (Note 1)		E _{AS}	394	mJ
Reverse diode dv/dt (Note 2)		dv/dt	4.5	V/ns
MOSFET dv/dt ruggedness (Note 3)		dv/dt	50	V/ns
Operation Junction Temperature Range		T _J	-55~+150	°C
Storage Temperature Range		T _{stg}	-55~+150	°C

THERMAL CHARACTERISTICS

Characteristics	Symbol	Rating	Unit
Thermal Resistance, Junction-to-Case	R _{θJC}	1.2	°C/W
Thermal Resistance, Junction-to-Ambient	R _{θJA}	62.0	°C/W

ELECTRICAL CHARACTERISTICS (T_c=25°C UNLESS OTHERWISE NOTED)

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Drain -Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	650	--	--	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =650V, V _{GS} =0V	--	--	1.0	μA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±30V, V _{DS} =0V	--	--	±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{GS} = V _{DS} , I _D =250μA	2.0	--	4.0	V
Static Drain- Source On State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =4.0A	--	1.2	1.4	Ω
Gate Resistance	R _g	f=1.0MHz		2.6		Ω
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, f=1.0MHz	--	933	--	pF
Output Capacitance	C _{oss}		--	87	--	
Reverse Transfer Capacitance	C _{rss}		--	6.4	--	
Turn-on Delay Time	t _{d(on)}	V _{DD} =325V, I _D =8.0A, R _G =25Ω (Note 4, 5)	--	17	--	ns
Turn-on Rise Time	t _r		--	36	--	
Turn-off Delay Time	t _{d(off)}		--	46	--	
Turn-off Fall Time	t _f		--	34	--	
Total Gate Charge	Q _g	V _{DS} =520V, I _D =8.0A, V _{GS} =10V (Note 4, 5)	--	23	--	nC
Gate-Source Charge	Q _{gs}		--	7.2	--	
Gate-Drain Charge	Q _{gd}		--	9.4	--	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I_S	Integral Reverse P-N Junction Diode in the MOSFET	--	--	8.0	A
Pulsed Source Current	I_{SM}		--	--	32	
Diode Forward Voltage	V_{SD}	$I_S=8.0A$, $V_{GS}=0V$	--	--	1.4	V
Reverse Recovery Time	T_{rr}	$I_S=8.0A$, $V_{GS}=0V$, $dI_F/dt=100A/\mu s$ (Note 4)	--	583	--	ns
Reverse Recovery Charge	Q_{rr}		--	3.5	--	μC

Notes:

1. $L=30mH$, $I_{AS}=4.8A$, $V_{DD}=100V$, $R_G=25\Omega$, starting $T_J=25^\circ C$;
2. $V_{DS}=0\sim 400V$, $I_{SD}\leq 8.0A$, $T_J=25^\circ C$;
3. $V_{DS}=0\sim 480V$;
4. Pulse Test: Pulse width $\leq 300\mu s$, Duty cycles $\leq 2\%$;
5. Essentially independent of operating temperature.

TYPICAL CHARACTERISTICS

Figure 1. On-Region Characteristics

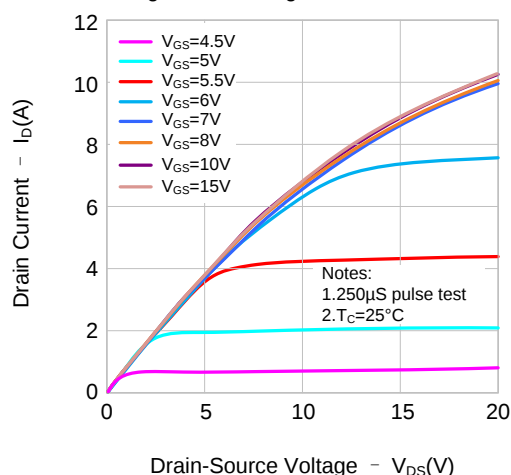


Figure 2. Transfer Characteristics

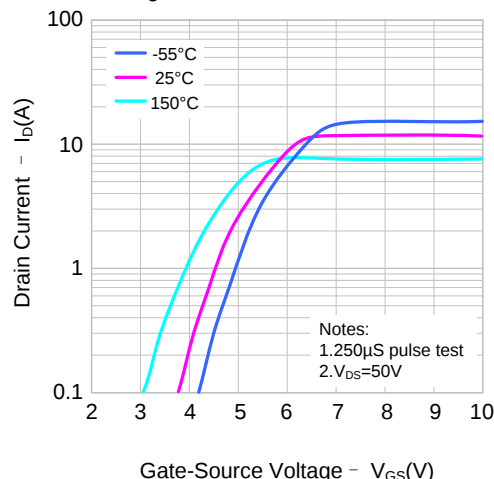


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

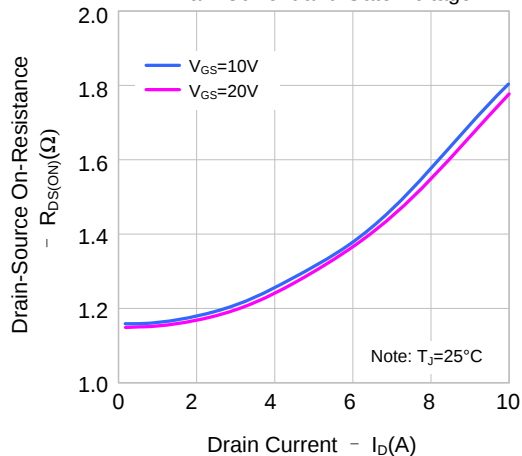
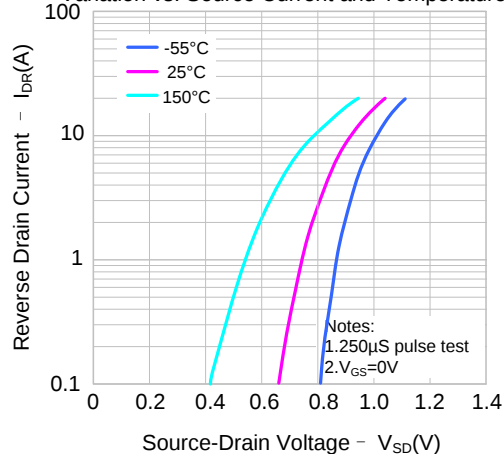


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature



TYPICAL CHARACTERISTICS (CONTINUED)

Figure 5. Capacitance Characteristics

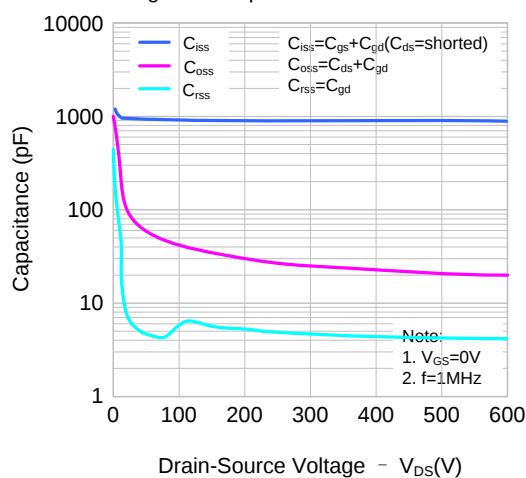


Figure 6. Gate Charge Characteristics

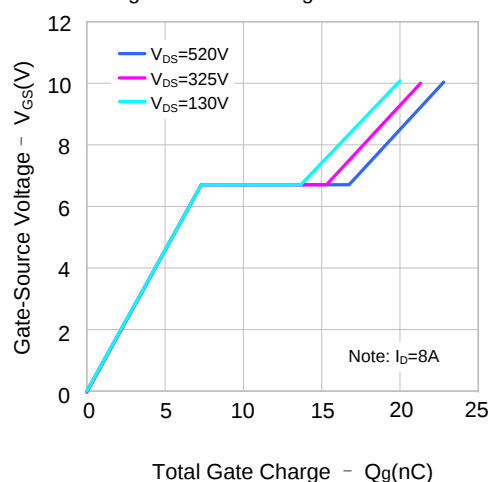


Figure 7. Breakdown Voltage Variation vs. Temperature

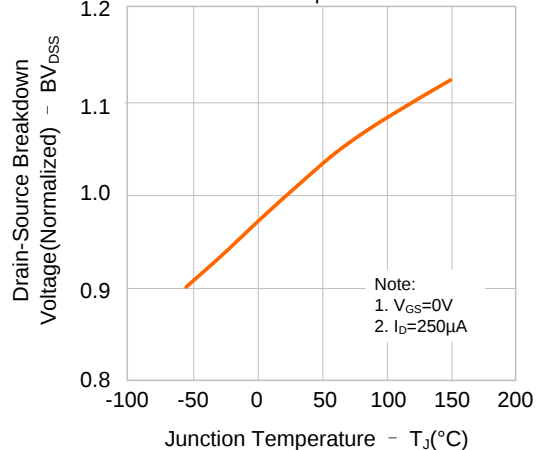


Figure 8. On-resistance Variation vs. Temperature

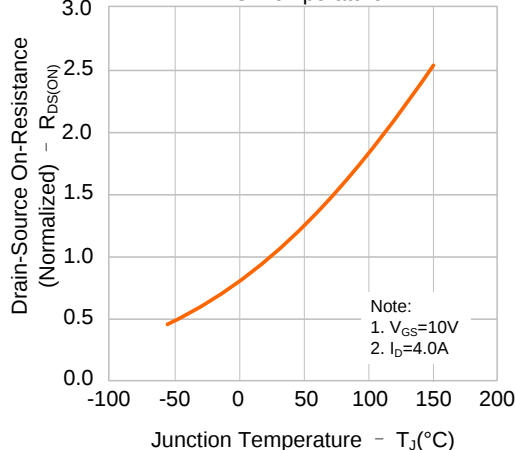


Figure 9. Max. Safe Operating Area

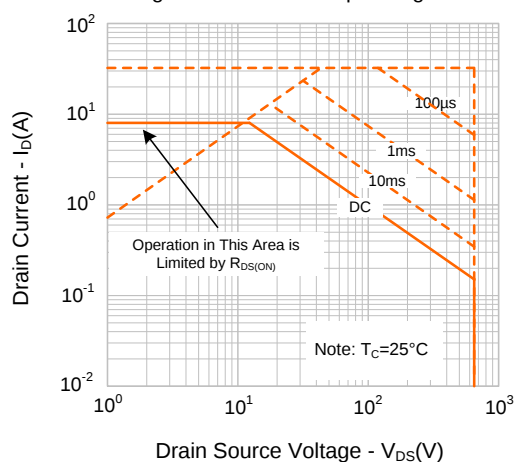
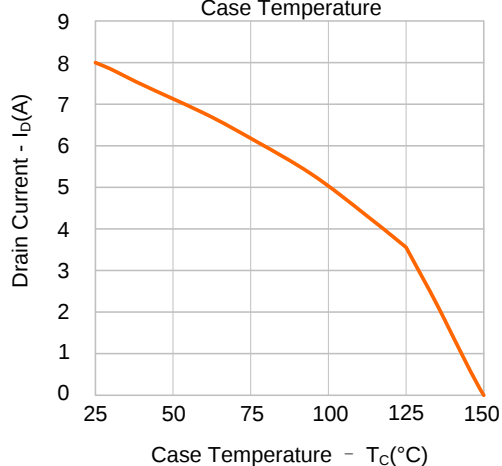
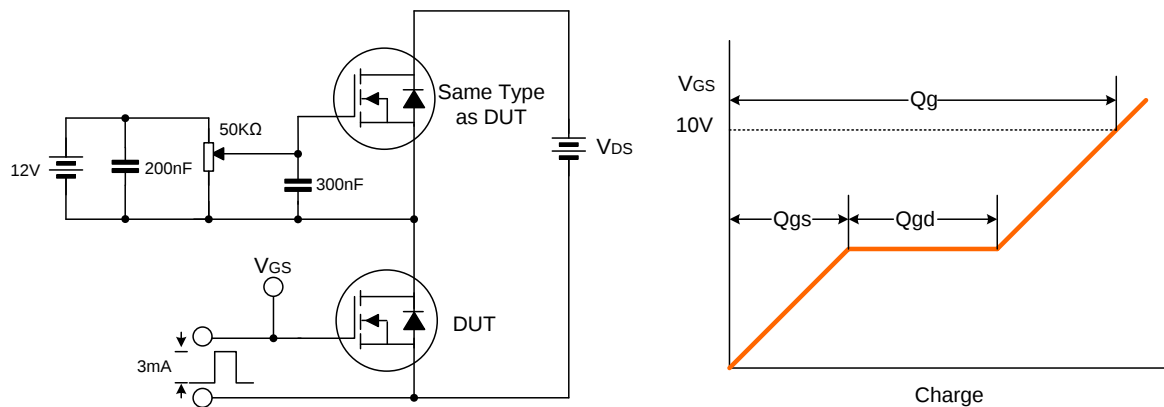


Figure 10. Maximum Drain Current vs. Case Temperature

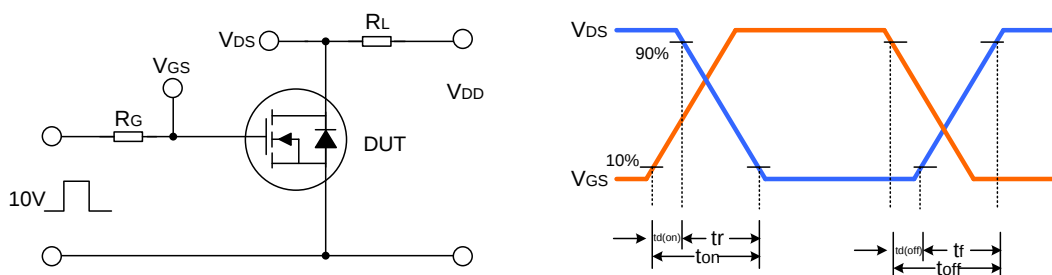


TYPICAL TEST CIRCUIT

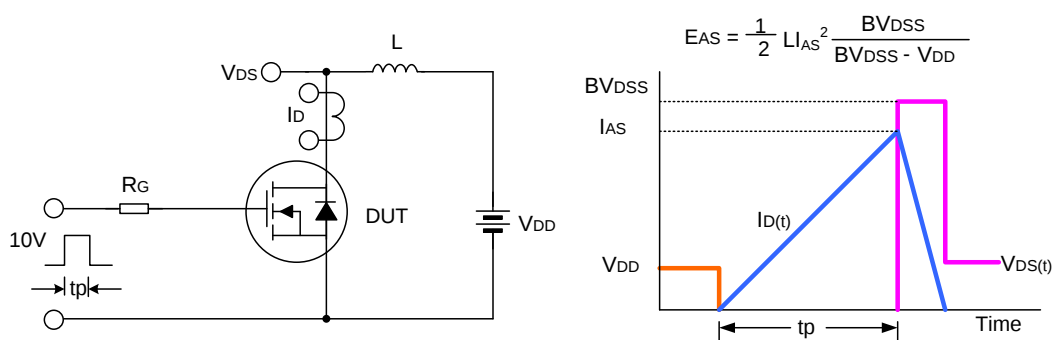
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform



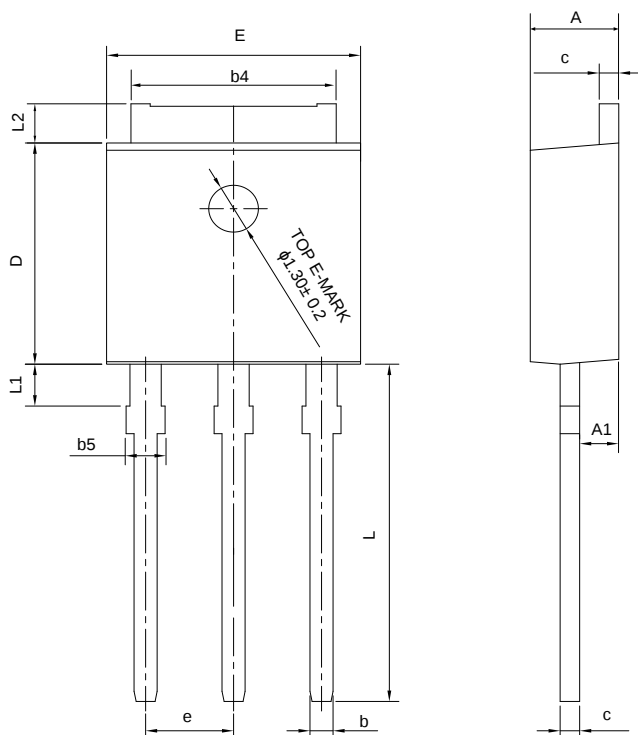
Unclamped Inductive Switching Test Circuit & Waveform



PACKAGE OUTLINE

TO-251J-3L

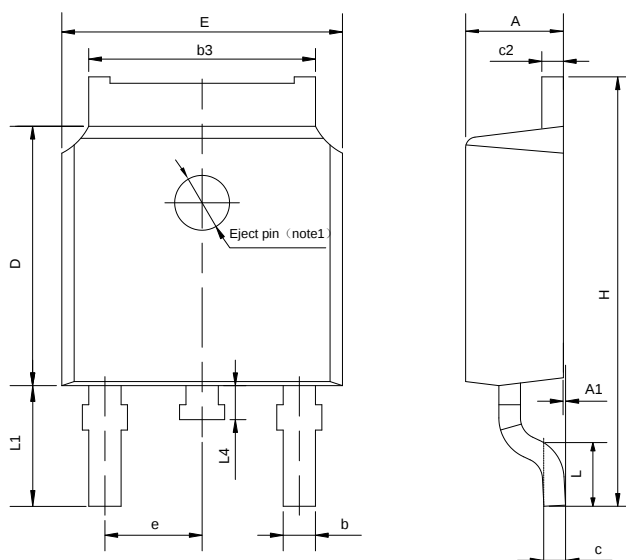
UNIT: mm



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.18	2.30	2.39
A1	0.89	1.00	1.14
b	0.56	—	0.89
b4	4.95	5.33	5.46
b5	—	—	1.05
c	0.46	—	0.61
D	5.97	6.10	6.27
E	6.35	6.60	6.73
e	2.29 BCS		
L	8.89	9.30	9.65
L1	0.95	—	1.50
L2	0.89	—	1.27

TO-252-2L

UNIT: mm



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.10	2.30	2.50
A1	0	—	0.127
b	0.66	0.76	0.89
b3	5.10	5.33	5.46
c	0.45	—	0.65
c2	0.45	—	0.65
D	5.80	6.10	6.40
E	6.30	6.60	6.90
e	2.30TYP		
H	9.60	10.10	10.60
L	1.40	1.50	1.70
L1	2.90REF		
L4	0.60	0.80	1.00

NOTE1 : There are two conditions for this position:has an eject pin or has no eject pin.

Important notice :

- The instructions are subject to change without notice! Customers should obtain the latest relevant information before placing orders and should verify that such information is complete and current.
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- Website: <http://www.silan.com.cn>

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Revision History:

1. Deleted NOMENCLATURE
2. Modify Important notice

Rev.: **1.0**

Revision History:

1. First release